



**PATENT APPLICATION**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Jun-ichiro FURIHATA et al.

Group Art Unit: 2812

Application No.: 09/787,038

Examiner: C. Lattin

Filed: March 13, 2001

Docket No.: 108868

For: METHOD OF PRODUCING A BONDED WAFER AND THE BONDED WAFER

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In reply to the July 25, 2003, Office Action, and in conjunction with the Request for Continued Examination filed herewith, the following is submitted:

**Amendments to the Claims** are reflected in the listing of claims; and

**Remarks.**

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